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(54) Title: COMPOSITION AND METHOD FOR FABRICATION OF NICKEL INTERCONNECTS

EXAMPLES 1 - 4

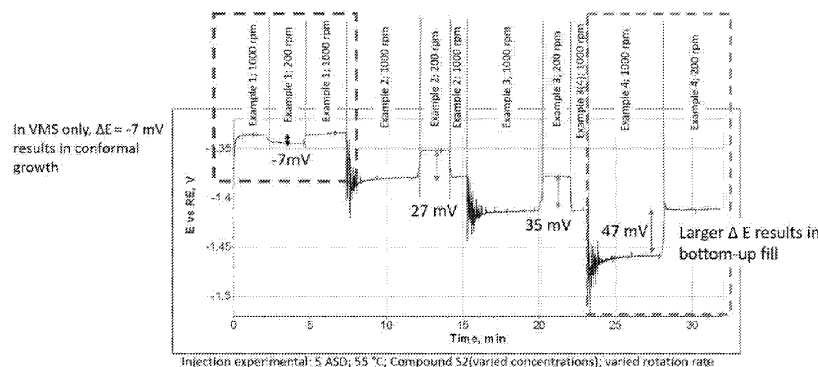


Figure 1

(57) **Abstract:** A nickel electrodeposition composition for via fill or barrier nickel interconnect fabrication comprising: (a) a source of nickel ions; (b) one or more polarizing additives; and (c) one or more depolarizing additives. The nickel electrodeposition composition may include various additives, including suitable acids, surfactants, buffers, and/or stress modifiers to produce bottom-up filling of vias and trenches.

[Continued on next page]

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